

Description

The HSSN3139 is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

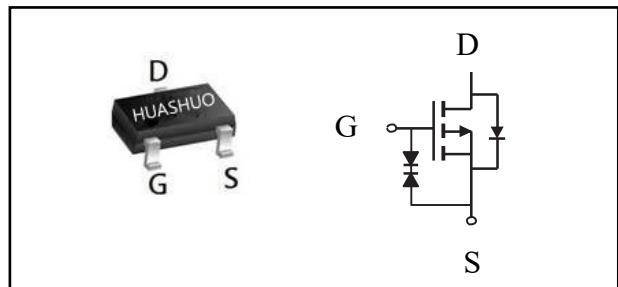
The HSSN3139 meet the RoHS and Green Product requirement with full function reliability approved.

Product Summary

V _{DS}	-20	V
R _{DSON,Max}	630	mΩ
I _D	-0.5	A

- Super Low Gate Charge
- Low Threshold
- High-Side Switching
- Advanced high cell density Trench technology

SOT 323 Pin Configurations



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-20	V
V _{GS}	Gate-Source Voltage	±8	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ -4.5V ₁	-0.5	A
I _{DM}	Pulsed Drain Current ₂	-2	A
P _D @T _A =25°C	Total Power Dissipation ₃	0.35	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ₁	---	357	°C/W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250μA	-20	---	---	V
△BV _{DSS} /△T _J	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA	---	-0.014	---	V/°C
R _{DSON}	Static Drain-Source On-Resistance ²	V _{GS} =-4.5V , I _D =-0.5A	---	560	630	mΩ
		V _{GS} =-2.5V , I _D =-0.3A	---	790	900	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250μA	-0.5	-0.67	-1.1	V
△V _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	3.95	---	mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-16V , V _{GS} =0V , T _J =25°C	---	---	-1	uA
		V _{DS} =-16V , V _{GS} =0V , T _J =55°C	---	---	-5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±10V , V _{DS} =0V	---	---	±20	nA
Q _g	Total Gate Charge (-4.5V)	V _{DS} =-10V , V _{GS} =-2.5V , I _D =-0.5A	---	1	---	nC
Q _{gs}	Gate-Source Charge		---	0.2	---	
Q _{gd}	Gate-Drain Charge		---	0.26	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =-10V , V _{GS} =-4.5V , R _G =1Ω, I _D =-0.5A	---	9	---	ns
T _r	Rise Time		---	10	---	
T _{d(off)}	Turn-Off Delay Time		---	10	---	
T _f	Fall Time		---	8	---	
C _{iss}	Input Capacitance	V _{DS} =-10V , V _{GS} =0V , f=1MHz	---	45	---	pF
C _{oss}	Output Capacitance		---	15	---	
C _{rss}	Reverse Transfer Capacitance		---	10	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

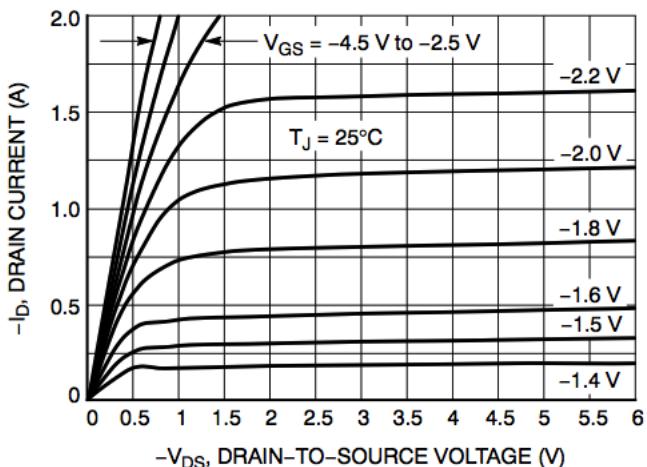


Figure 1. On-Region Characteristics

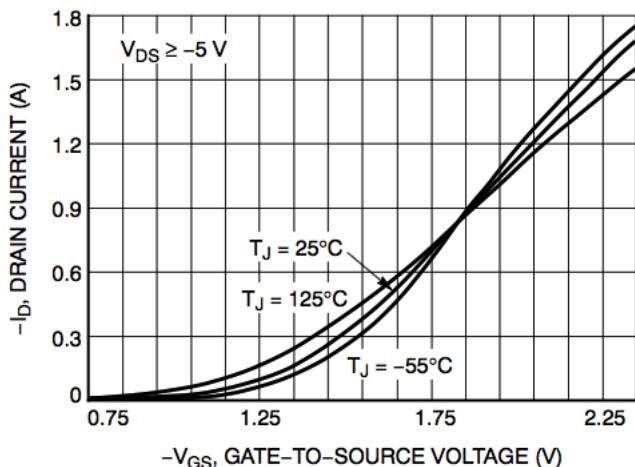


Figure 2. Transfer Characteristics

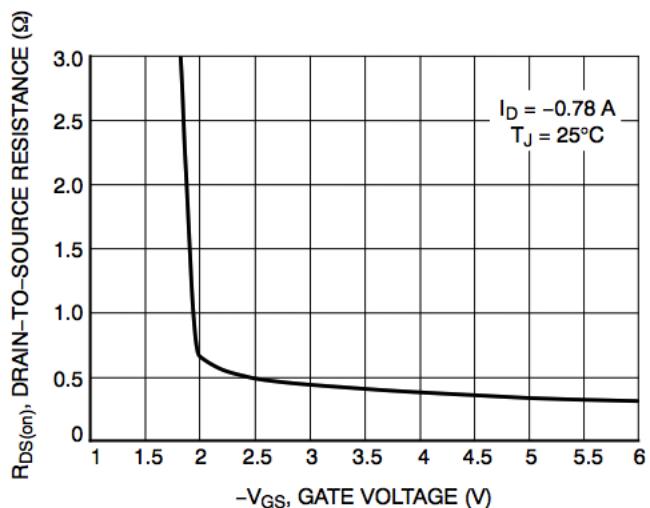


Figure 3. On-Resistance vs. Gate-to-Source Voltage

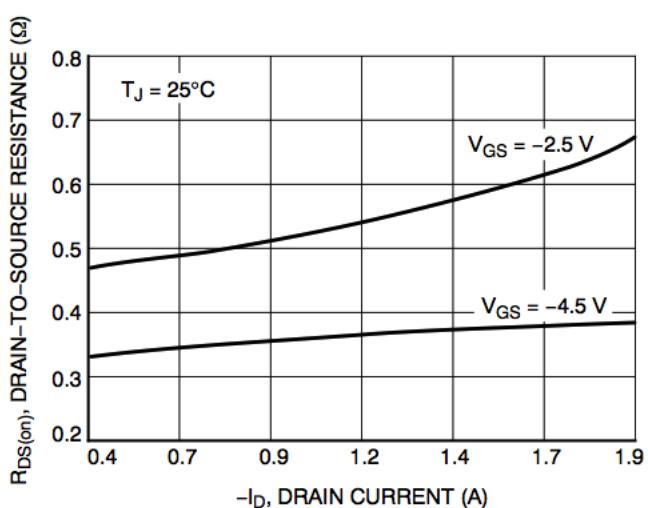


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

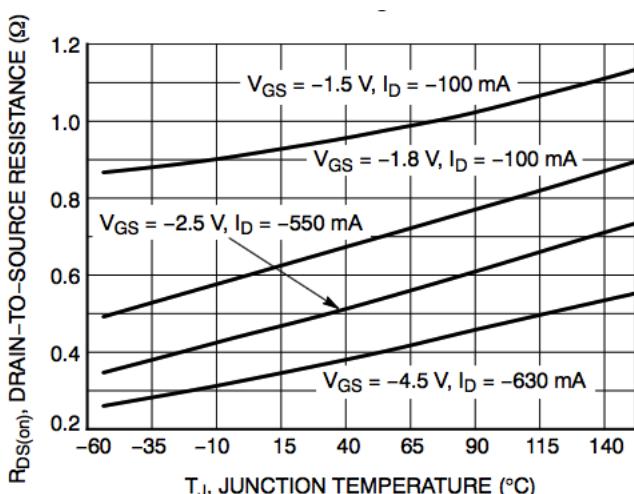


Figure 5. On-Resistance Variation with Temperature

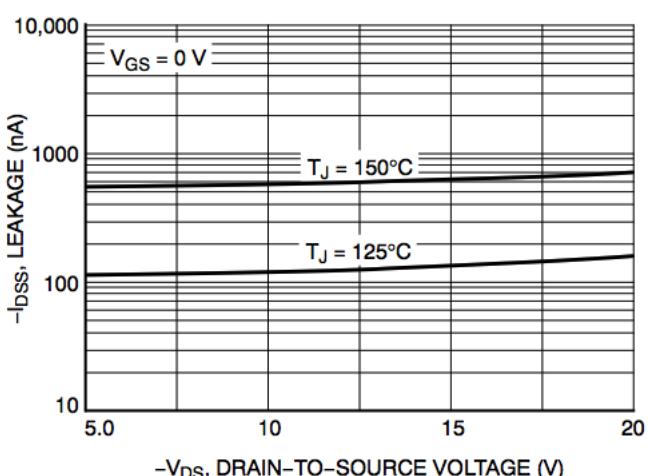


Figure 6. Drain-to-Source Leakage Current vs. Voltage

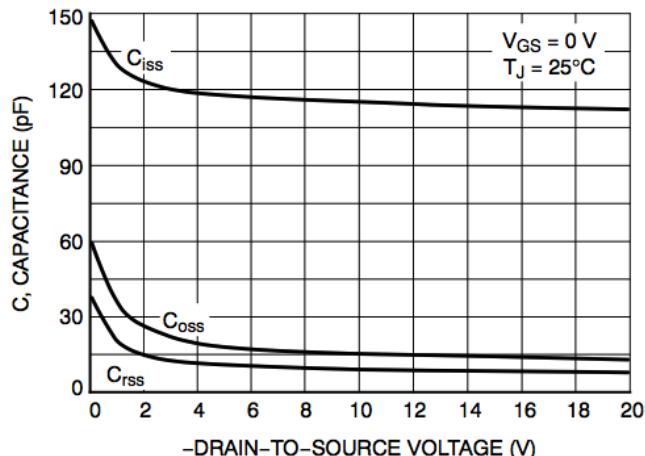


Figure 7. Capacitance Variation

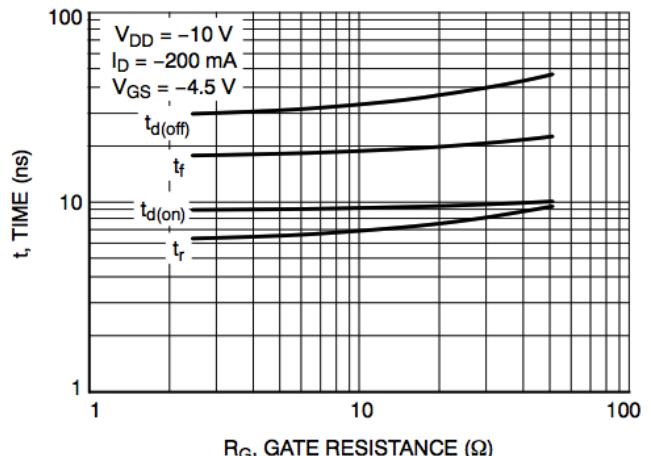


Figure 8. Resistive Switching Time Variation
vs. Gate Resistance

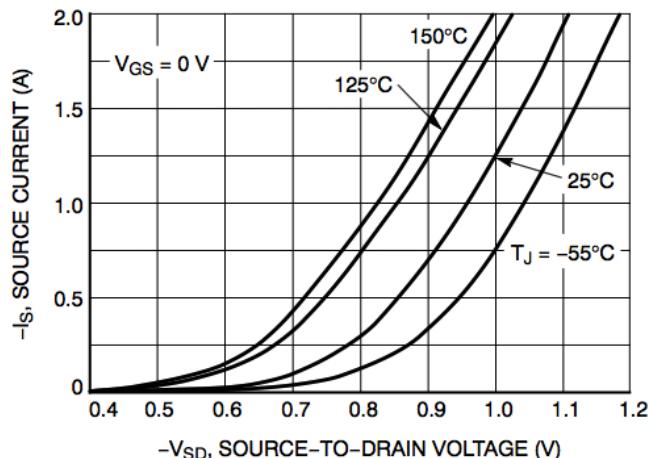
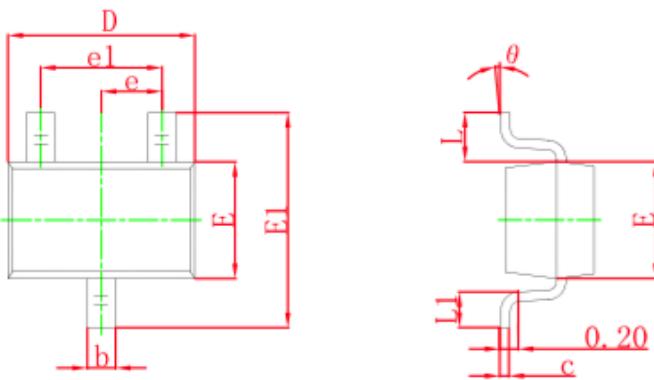


Figure 9. Diode Forward Voltage vs. Current

Ordering Information

Part Number	Package code	Packaging
HSSN3139	SOT-323	3000/Tape&Reel



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°